Nürnberg 16–18 May 2017



smthybridpackaging



DCIM EUROPE



equipment for semiconductor power modules production and test



... from DBC Mastercard to the finished power module.

DBC MASTERCARD DIVIDER

from mastercard magazine to magazines of single modules MV inspection no any human touch fully automatic

SELECTIVE SOLDERING of POWER LEADS on DBC

no oven required no fixtures multiproduct quick set-up fully automatic

PRESSFIT PIN on DBC SELECTIVE SOLDERING

pin cutting from reels 3D laser AOI control robotic arms handling no oven, no fixtures required multiproduct; quick set-up fully automatic

DISPENSING

glue dispensing UV curing option: in VACUUM silicones (A+B) dosing precision weighing fitting – pressing fully automatic





4.0 READY



ASSEMBLING - CASING DBC & baseplate

glue dispensing UV curing case attaching silicone (A+B) filling precision weighing bushes pressing 1 ton multiproduct - quick setup fully automatic

HOT IRON SELECTIVE SOLDERING power modules on PCB boards,

- ... odd components
- ... power connectors
- ... automotive parts
- 5 axis CNC equipment

HANDLER – MARKER for PARAMETRIC TESTER DBC & baseplate modules

cold & hot parametric test, high voltage insulation test laser marking - class sorting, machine vision controls multiproduct - fully automatic

HANDLER – MARKER for FULL POWER TESTER

DBC & baseplate modules

cold & hot dynamic test, high voltage insulation test laser marking - class sorting, machine vision controls multiproduct - fully automatic super quick setup









SMT2017.INDD

SINERGO



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ULTRASONIC TORSIONAL WELDING of power leads.

customized equipment semi and fully automatic. powered by Telsonic

WAFER TESTING MARKING LASER ABLATION

TRR measuring robotic wafer handling die laser ablation/killing cleanroom ready traceability + MES 5"-6" wafer; dice > 40 mils fully automatic

LASER SELECTIVE SOLDERING for power leads, wires, ceramic sensor, microelectronic devices, ...

powered by Sinergo Sinlas laser fully automatic – very high speed wire cutting + trimming, from reels cleanroom ready 3D AOI controls traceability + MES

WAFER TESTING robotic arm driven by machine vision test handler equipment die TRR measuring fully automatic wafer handling cleanroom ready traceability + MES

